

DATA SHEET

GENERAL PURPOSE CHIP RESISTORS RC2512 (Pb Free) 5%; 1%



YAGEO







Chip Resistor Surface Mount

SERIES

2512 (Pb Free)

SCOPE

This specification describes RC2512 series chip resistors with lead-free terminations made by thick film process.

ORDERING INFORMATION

Part number is identified by the series, size, tolerance, packing type, temperature coefficient, taping reel and resistance value.

YAGEO ORDERING CODE

CTC CODE

RC2512 <u>X X X XX XXXX L</u> (I) (2) (3) (4) (5) (6)

(I) TOLERANCE

 $F = \pm 1\%$ $J = \pm 5\%$

(2) PACKAGING TYPE

K = Embossed/ taping reel

(3) TEMPERATURE COEFFICIENT OF RESISTANCE

- = Base on spec

(4) TAPING REEL

07 = 7 inch dia, Reel

(5) RESISTANCE VALUE

5R6, 56R, 560R, 5K6, 56K, 22M.

(6) RESISTOR TERMINATIONS

L = Lead free terminations (pure Tin)

ORDERING EXAMPLE

The ordering code of a RC2512 chip resistor, value 56 Ω with ±1% tolerance, supplied in 7-inch tape reel is: RC2512FK-0756RL.

NOTE

- The "L" at the end of the code is only for ordering. On the reel label, the standard CTC will be mentioned an additional stamp "LFP"= lead free production.
- Products with lead in terminations fulfil the same requirements as mentioned in this datasheet.
- Products with lead in terminations will be phased out in the coming months (before July 1st, 2006)





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MARKING

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RC2512



E-24 series: 3 digits

First two digits for significant figure and 3rd digit for number of zeros



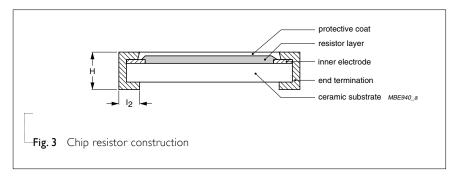
Both E-24 and E-96 series: 4 digits

First three digits for significant figure and 4th digit for number of zeros

For marking codes, please see EIA-marking code rules in data sheet "Chip resistors instruction".

CONSTRUCTION

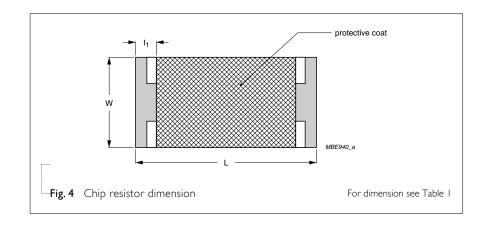
The resistors are constructed out of a high-grade ceramic body. Internal metal electrodes are added at each end and connected by a resistive paste. The composition of the paste is adjusted to give the approximate required resistance and laser cutting of this resistive layer that achieves tolerance trims the value. The resistive layer is covered with a protective coat and printed with the



resistance value. Finally, the two external terminations (pure Tin) are added. See fig. 3.

<u>DIMENSIONS</u>

Table I	
TYPE	RC2512
L (mm)	6.35 ±0.10
W (mm)	3.10 ±0.15
H (mm)	0.55 ±0.10
I _I (mm)	0.60 ±0.20
I ₂ (mm)	0.50 ±0.20





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ELECTRICAL CHARACTERISTICS

Table 2

CHARACTERISTICS		RC2512 1 W
Operating Temperature Range	– 55	°C to +155 °C
Maximum Working Voltage		200 V
Maximum Overload Voltage		500 V
Dielectric Withstanding Voltage		500 V
	5% (E24)	I Ω to 22 M Ω
Resistance Range	1% (E96)	I Ω to I0 M Ω
	Zero Ohm Ju	ımper < 0.05 Ω
Temperature Coefficient	$10 \Omega < R \le 10 M\Omega$	±100 ppm/°C
Temperature Coemcient	$R \le 10 \Omega$; $R > 10 M\Omega$	±200 ppm/°C
Jumper Criteria	Rated Current	2.0 A
Jumper Criteria	Maximum Current	10.0 A

<u>FOOTPRINT AND SOLDERING</u> PROFILES

For recommended footprint and soldering profiles, please see the special data sheet "Chip resistors mounting".

ENVIRONMENTAL DATA

For material declaration information (IMDS-data) of the products, please see the separated info "Environmental data".

PACKING STYLE AND PACKAGING QUANTITY

Table 3 Packing style and packaging quantity

PRODUCT TYPE	PACKING STYLE	REEL DIMENSION	QUANTITY PER REEL
RC2512	Embossed taping reel (K)	7" (178 mm)	4,000 units

NOTE

1. For embossed tape and reel specification/dimensions, please see the special data sheet "Packing" document.

FUNCTIONAL DESCRIPTION

POWER RATING

RC2512 rated power at 70°C is I W

RATED VOLTAGE

The DC or AC (rms) continuous working voltage corresponding to the rated power is determined by the following formula:

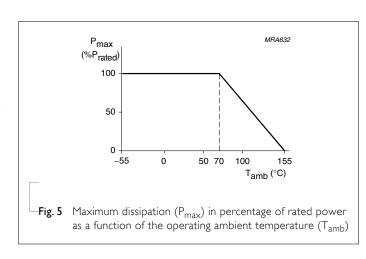
$$V = \sqrt{(P \times R)}$$

Where

V=Continuous rated DC or AC (rms) working voltage (V)

P=Rated power (W)

R=Resistance value (Ω)





TESTS AND REQUIREMENTS

Table 4 Test condition, procedure and requirements

TEST	TEST METHOD	PROCEDURE	REQUIREMENTS
Temperature Coefficient of	MIL-STD-202F-method 304; JIS C 5202-4.8	At +25/–55 °C and +25/+125 °C	Refer to table 2
Resistance	,10 0 0202 1.0	Formula:	
(T.C.R.)		T.C.R= $\frac{R_2-R_1}{R_1(t_2-t_1)} \times 10^6 \text{ (ppm/°C)}$	
		Where t_1 =+25 °C or specified room temperature	
		t_2 =–55 °C or +125 °C test temperature	
		R ₁ =resistance at reference temperature in ohms	
		R ₂ =resistance at test temperature in ohms	
Thermal Shock	MIL-STD-202F-method 107G;	At -65 (+0/-10) °C for 2 minutes and at +155	$\pm (0.5\% \pm 0.05 \ \Omega)$ for 1% tol.
	IEC 60115-1 4.19	(+10/-0) °C for 2 minutes; 25 cycles	\pm (1.0%+0.05 Ω) for 5% tol.
Low	MIL-R-55342D-Para 4.7.4	At -65 (+0/-5) °C for I hour, RCWV applied	\pm (0.5%+0.05 Ω) for 1% tol .
Temperature		for 45 (+5/–0) minutes	$\pm (1.0\% + 0.05 \ \Omega)$ for 5% tol.
Operation			No visible damage
Short Time	MIL-R-55342D-Para 4.7.5;	2.5 × RCWV applied for 5 seconds at room	\pm (1.0%+0.05 Ω) for 1% tol.
Overload	IEC 60115-1 4.13	temperature	$\pm (2.0\% + 0.05 \ \Omega)$ for 5% tol.
			No visible damage
Insulation	MIL-STD-202F-method 302;	RCOV for I minute	≥10 GΩ
Resistance	IEC 60115-1 4.6.1.1	Type RC2512	
		Voltage (DC) 500 V	
Dielectric	MIL-STD-202F-method 301;	Maximun voltage (V _{rms}) applied for 1 minute	No breakdown or flashover
Withstand	IEC 60115-1 4.6.1.1	Type RC2512	
Voltage		Voltage (AC) 500 V _{rms}	
Resistance to	MIL-STD-202F-method 210C;	Unmounted chips; 260 ±5 °C for 10 ±1	\pm (0.5%+0.05 Ω) for 1% tol.
Soldering	IEC 60115-1 4.18	seconds	\pm (1.0%+0.05 Ω) for 5% tol.
Heat			No visible damage
Life	MIL-STD-202F-method 108A;	At 70±2 °C for 1,000 hours; RCWV applied for	$\pm (1\% + 0.05 \ \Omega)$ for 1% tol.
	IEC 60115-1 4.25.1	1.5 hours on and 0.5 hour off	$\pm(3\% {+} 0.05~\Omega)$ for 5% tol.

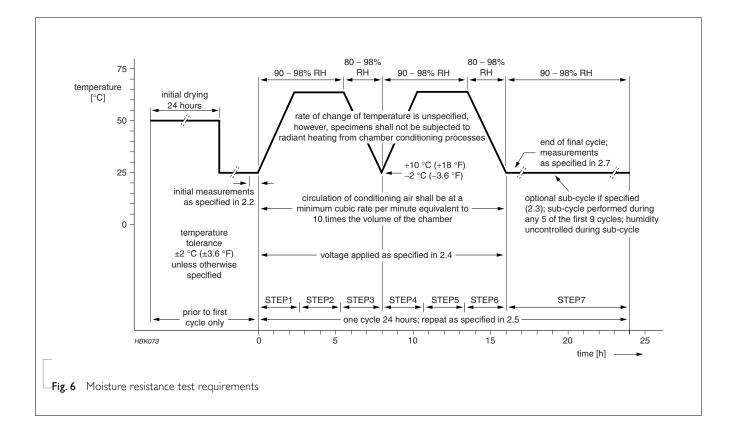


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ST	TEST METHOD	PROCEDURE	REQUIREMENTS	
Solderability	MIL-STD-202F-method 208A;	Solder bath at 245±3 °C	Well tinned (≥95% covered) No visible damage	
	IEC 60115-1 4.17	Dipping time: 2±0.5 seconds		
Bending	JIS C 5202.6.14;	Resistors mounted on a 90 mm glass epoxy	\pm (1.0%+0.05 Ω) for 1% tol. \pm (1.0%+0.05 Ω) for 5% tol. No visible damage	
Strength	IEC 60115-1 4.15	resin PCB (FR4)		
		Bending: 2 mm		
Resistance to Solvent	MIL-STD-202F-method 215;	Isopropylalcohol (C ₃ H ₇ OH) or dichloromethane	No smeared	
	IEC 60115-1 4.29	(CH ₂ Cl ₂) followed by brushing		
Noise	JIS ⊂ 5202 5.9;	Maximum voltage (V _{rms}) applied.	Resistors range	Value
	IEC 60115-1 4.12		R < 100 Ω	10 dE
			$100 \Omega \le R < 1 K\Omega$	24 dE
			I KΩ ≤ R < 10 KΩ	34 dE
			$10 \text{ K}\Omega \leq R < 100 \text{ K}\Omega$	44 dE
			$100 \text{ K}\Omega \leq R < 1 \text{ M}\Omega$	46 dl
			$I M\Omega \le R \le 22 M\Omega$	48 dl
Humidity (steady state)	JIS C 5202 7.5; IEC 60115-8 4.24.8	1,000 hours; 40±2 °C; 93(+2/–3)% RH RCWV applied for 1.5 hours on and 0.5 hour off	$\pm (0.5\% + 0.05 \ \Omega)$ for 1% $\pm (2.0\% + 0.05 \ \Omega)$ for 5%	
(steady state)	•		$\pm (2.0\% + 0.05 \ \Omega)$ for 5%	
	IEC 60115-8 4.24.8	RCWV applied for 1.5 hours on and 0.5 hour off		
(steady state)	IEC 60115-8 4.24.8 EIA/IS 4.13B;	RCWV applied for 1.5 hours on and 0.5 hour off Solder bath at 260 \pm 5 $^{\circ}$ C	$\pm (2.0\% + 0.05 \ \Omega)$ for 5%	6 tol.
(steady state) Leaching Intermittent	IEC 60115-8 4.24.8 EIA/IS 4.13B; IEC 60115-8 4.18	RCWV applied for 1.5 hours on and 0.5 hour off Solder bath at 260±5 °C Dipping time: 30±1 seconds At room temperature; 2.5 × RCWV applied for 1 second on and 25 seconds off; total 10,000	$\pm (2.0\% + 0.05~\Omega)$ for 5% No visible damage $\pm (1.0\% + 0.05~\Omega)$ for 1%	6 tol.
Leaching Intermittent Overload Resistance to	IEC 60115-8 4.24.8 EIA/IS 4.13B; IEC 60115-8 4.18 JIS C 5202 5.8	RCWV applied for 1.5 hours on and 0.5 hour off Solder bath at 260±5 °C Dipping time: 30±1 seconds At room temperature; 2.5 × RCWV applied for 1 second on and 25 seconds off; total 10,000 cycles	$\pm (2.0\% + 0.05~\Omega)$ for 5% No visible damage $\pm (1.0\% + 0.05~\Omega)$ for 1%	6 tol. 6 tol. 6 tol.
Leaching Intermittent Overload Resistance to Vibration	IEC 60115-8 4.24.8 EIA/IS 4.13B; IEC 60115-8 4.18 JIS C 5202 5.8 On request	RCWV applied for 1.5 hours on and 0.5 hour off Solder bath at 260±5 °C Dipping time: 30±1 seconds At room temperature; 2.5 × RCWV applied for 1 second on and 25 seconds off; total 10,000 cycles On request	$\pm (2.0\% + 0.05~\Omega)$ for 5% No visible damage $\pm (1.0\% + 0.05~\Omega)$ for 1% $\pm (2.0\% + 0.05~\Omega)$ for 5%	6 tol. 6 tol. 6 tol. tol.

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REVISION HISTORY

REVISION	DATE	CHANGE NOTIFICATION	DESCRIPTION
Version 2	Oct 06, 2004	-	- Test method and procedure updated